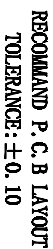


A

MAPX	MODIFICATION	DRW	DATE



NOTES:

1. MATERIAL SPECIFICATION:

- 1) INSULATION MATERIAL: THERMOPLASTIC HALOGENFREE.
- 2) SHELL: COPPER ALLOY T-0.30mm
PLATING: NICKEL
- 3) TERMINAL: COPPER ALLOY T-0.25mm
PLATING: GOLD/TIN PLATED;

2. ELECTRICAL CHARACTERISTIC:

- 1) INSULATION RESISTANCE: 1000M Ω MIN;
- 2) CONTACT RESISTANCE: 30m Ω MAX;
- 3) WITHSTANDING VOLTAGE: 500V AC;

3. MECHANICAL CHARACTERISTICS:

- 1) INSERTION FORCE: 3.57Kgf Max;
- 2) EXTRACTION FORCE: 1.02Kgf Min;

Shenzhen Jing Tuo Jin Electronics Co., Ltd.

PRODUCT CHART DWG		Shenzhen Jing Tuo Jin Electronics Co., Ltd.			
公差—公差表		单位	制图	制图料号	916-451A2026Y10200
TOLERANCE UNLESS OTHERWISE		UNITS	DRAWINGS	PRODUCT PART NO	
X	±0.35 X.		审核	产品名数	8位A.4位零件ID/10位零件地址的零件地址的零件ID. 6
X	±0.20 X.	比例	审核	PRODUCT NO	
XX	±0.15 XX	日期	核准	方法	
XXX	±0.05 .XXX ±0.5*	DATE	核准	VER	AO
			APPD		